

<b>Notice of References Cited</b>	Application/Control No. 10/560,073		Applicant(s)/Patent Under Reexamination MASUKO ET AL.	
	Examiner ANISH DESAI		Art Unit 1794	Page 1 of 1

#### U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-2002/0048726 A1	04-2002	Kikkawa et al.	430/283.1
*	B	US-5,904,505	05-1999	Hotta et al.	438/124
*	C	US-5,690,837	11-1997	Nakaso et al.	216/17
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

#### FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	I					

#### NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Fujii Shinjiro, "Adhesive for Die Bonding and Preparation of Semiconductor Device", Machine translation of JP 2000-104040, pages 1-13, 04/11/2000.
	V	
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.